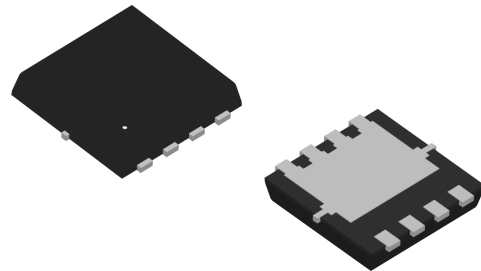


**WNM3030**
**Single N-Channel, 30V, 13A, Power MOSFET**
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

$V_{DS}$ (V)	Typical $R_{DS(on)}$ (m $\Omega$ )
30	5.5 @ $V_{GS}=10V$
	8.5 @ $V_{GS}=4.5V$


**Descriptions**

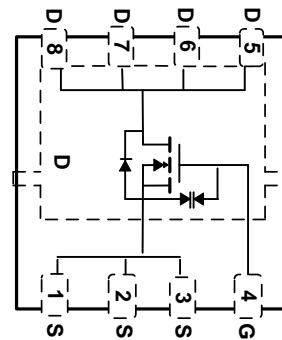
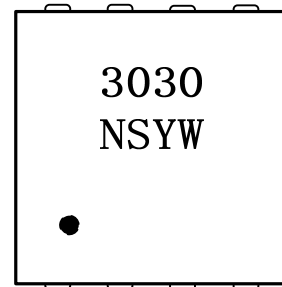
The WNM3030 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM3030 is Pb-free.

**Features**

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package PDFN3X3-8L-EP

**Applications**

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

**PDFN3x3-8L-EP**

**Pin configuration (Top view)**


3030 = Device Code  
 NS = Special Code  
 Y = Year  
 W = Week(A~z)

**Marking**
**Order information**

Device	Package	Shipping
WNM3030-8/TR	PDFN3x3-8L-EP	3000/Tape&Reel

**Absolute Maximum ratings**

Parameter	Symbol	10 s	Steady State	Unit	
Drain-Source Voltage	$V_{DS}$	30		V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$			
Continuous Drain Current <sup>a d</sup>	$I_D$	$T_A=25^\circ\text{C}$	13.2	9.6	A
		$T_A=70^\circ\text{C}$	10.5	7.7	
Maximum Power Dissipation <sup>a d</sup>	$P_D$	$T_A=25^\circ\text{C}$	3.1	1.7	W
		$T_A=70^\circ\text{C}$	2.0	1.1	
Continuous Drain Current <sup>b d</sup>	$I_D$	$T_A=25^\circ\text{C}$	9.2	7.5	A
		$T_A=70^\circ\text{C}$	7.4	6.0	
Maximum Power Dissipation <sup>b d</sup>	$P_D$	$T_A=25^\circ\text{C}$	1.5	1.0	W
		$T_A=70^\circ\text{C}$	1.0	0.6	
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	50		A	
Operating Junction Temperature	$T_J$	-55 to 150		$^\circ\text{C}$	
Lead Temperature	$T_L$	260		$^\circ\text{C}$	
Storage Temperature Range	$T_{stg}$	-55 to 150		$^\circ\text{C}$	

**Thermal resistance ratings**

Single Operation					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$t \leq 10 \text{ s}$	$R_{\theta JA}$	30	40	$^\circ\text{C/W}$
	Steady State		60	75	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$t \leq 10 \text{ s}$	$R_{\theta JA}$	65	82	
	Steady State		90	125	
Junction-to-Case Thermal Resistance	Steady State	$R_{\theta JC}$	16	22	

a Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper

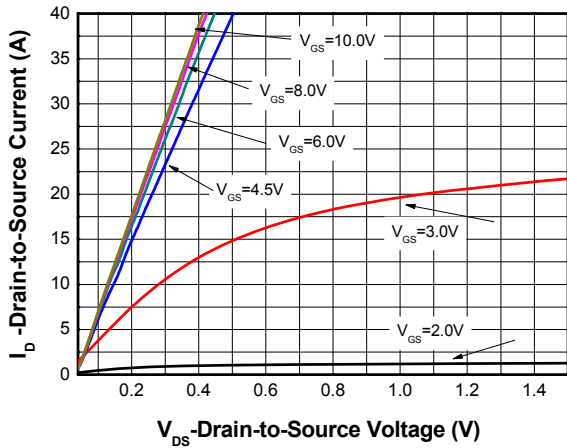
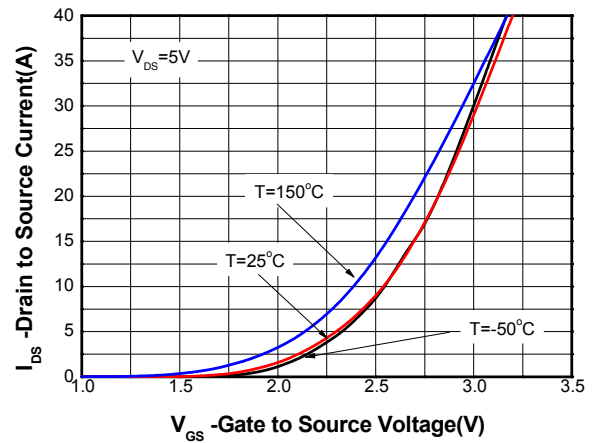
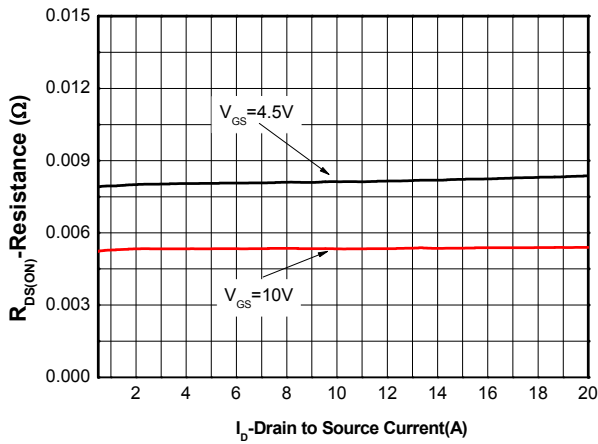
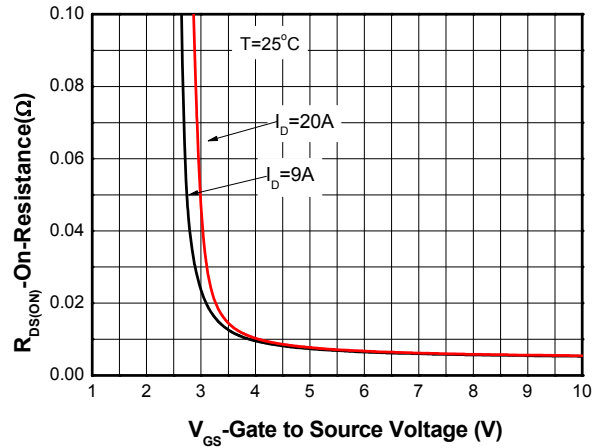
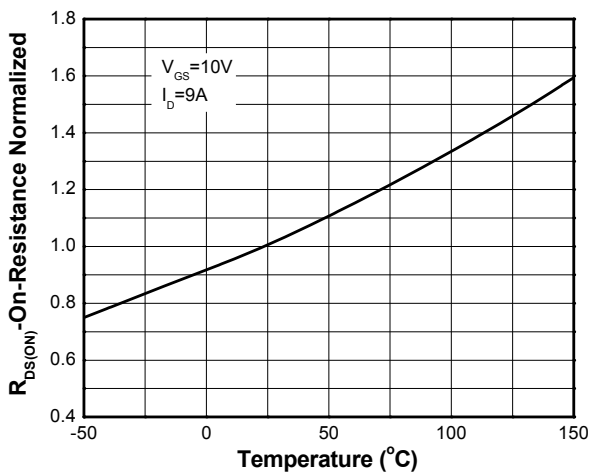
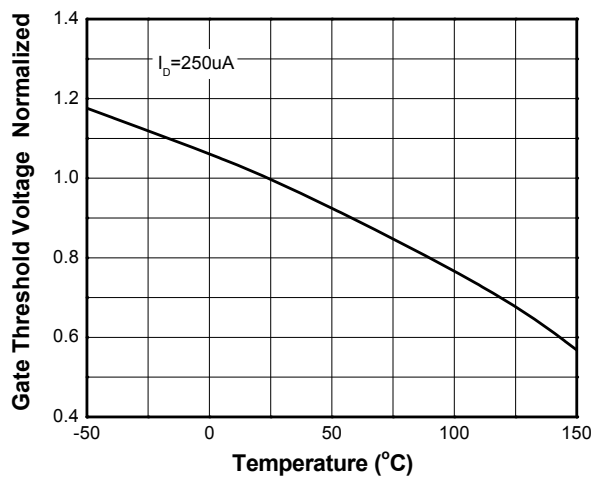
b Surface mounted on FR4 board using minimum pad size, 1oz copper

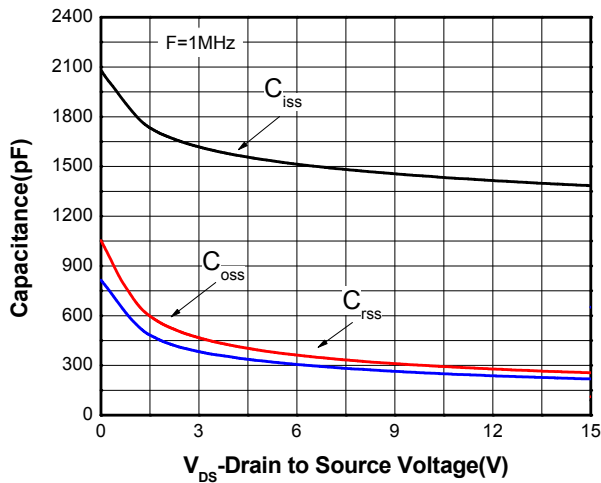
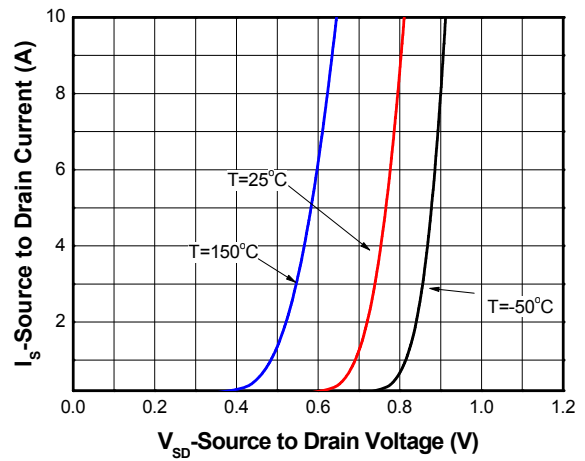
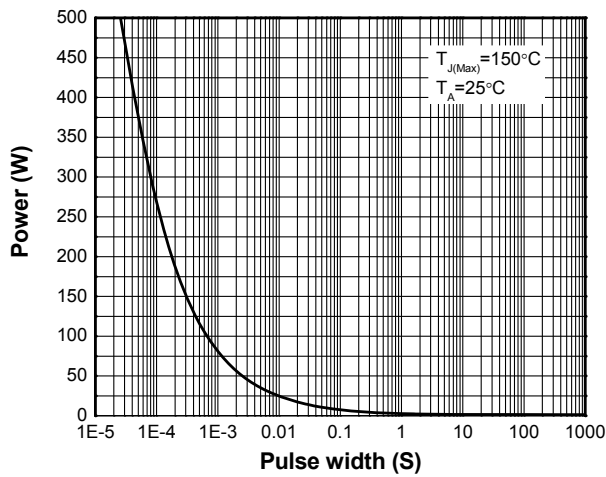
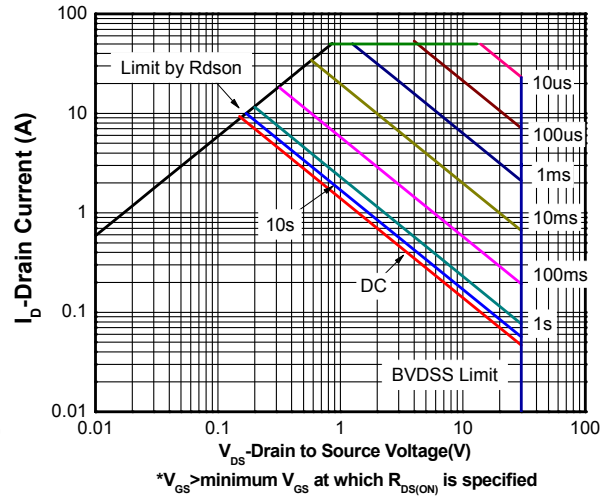
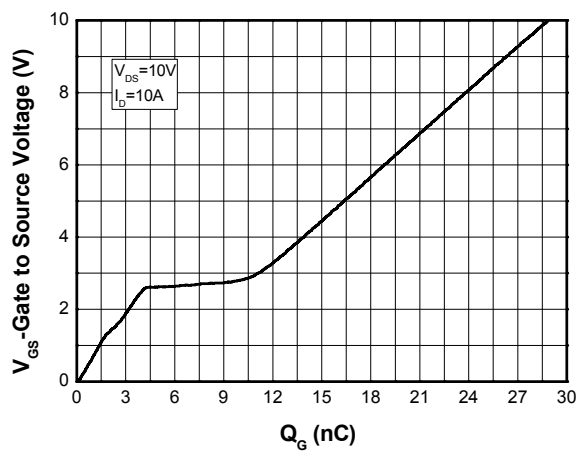
c Repetitive rating, pulse width limited by junction temperature,  $t_p=10\mu\text{s}$ , Duty Cycle=1%

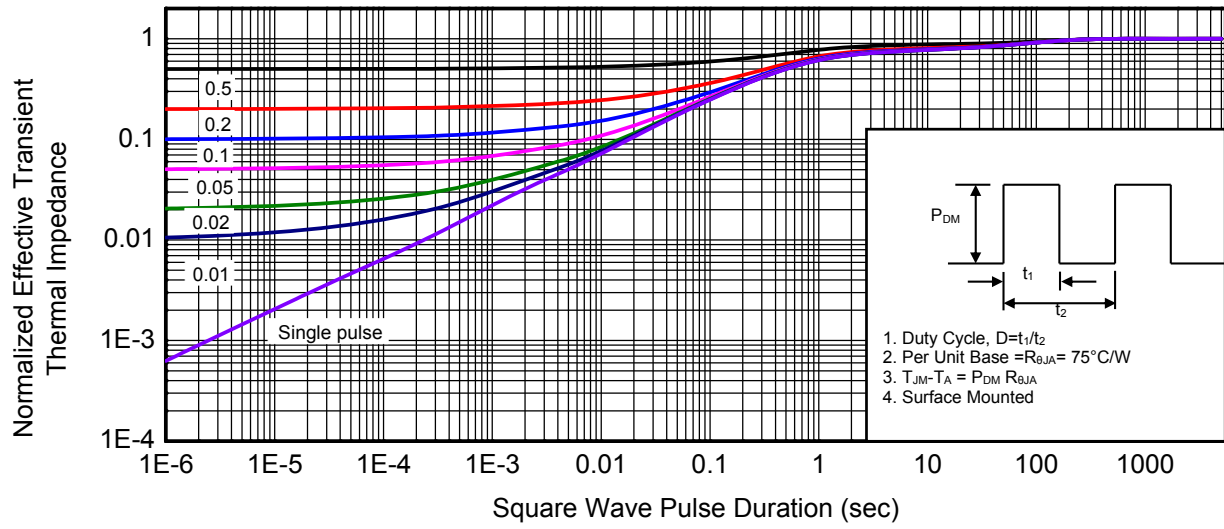
d Repetitive rating, pulse width limited by junction temperature  $T_J=150^\circ\text{C}$ .

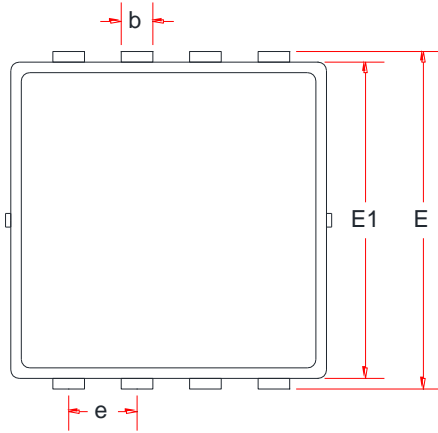
**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{V}$			$\pm 5$	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.0	1.4	2.0	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}, I_D = 10\text{A}$		5.5	9	m $\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 8\text{A}$		8.5	13	
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1.0\text{MHz}, V_{DS} = 15\text{ V}$		1384		pF
Output Capacitance	$C_{OSS}$			255		
Reverse Transfer Capacitance	$C_{RSS}$			218		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}, I_D = 10\text{ A}$		28.9		nC
Threshold Gate Charge	$Q_{G(TH)}$			1.3		
Gate-to-Source Charge	$Q_{GS}$			4.3		
Gate-to-Drain Charge	$Q_{GD}$			5.5		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}, R_L = 1.5\ \Omega, R_G = 3\ \Omega$		16.0		ns
Rise Time	$t_r$			9.0		
Turn-Off Delay Time	$t_d(OFF)$			55.0		
Fall Time	$t_f$			10.0		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 1\text{ A}$		0.7	1.2	V

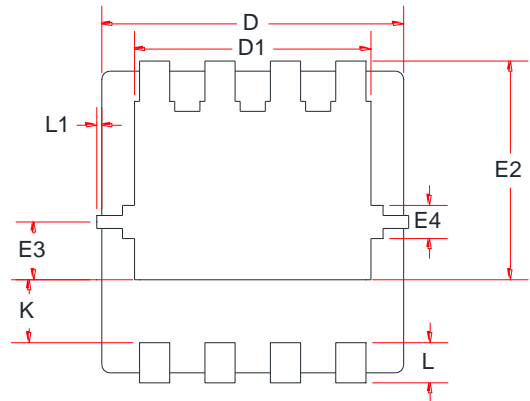
**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output characteristics**

**Transfer characteristics**

**On-Resistance vs. Drain current**

**On-Resistance vs. Gate-to-source voltage**

**On-Resistance vs. Junction temperature**

**Threshold voltage vs. Temperature**


**Capacitance**

**Body diode forward voltage**

**Single pulse power**

**Safe operating power**

**Gate Charge Characteristics**

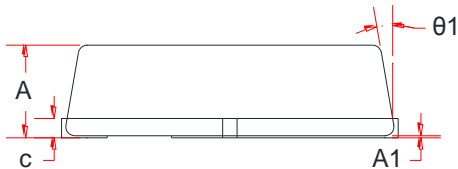
**Transient thermal response (Junction-to-Ambient)**


**Package outline dimensions**
**PDFN3x3-8L-EP**


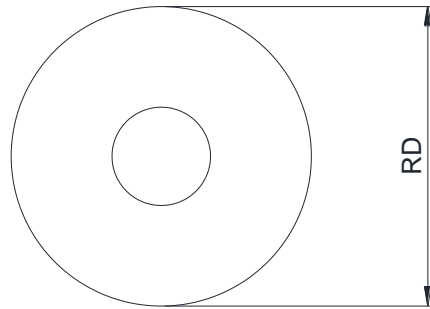
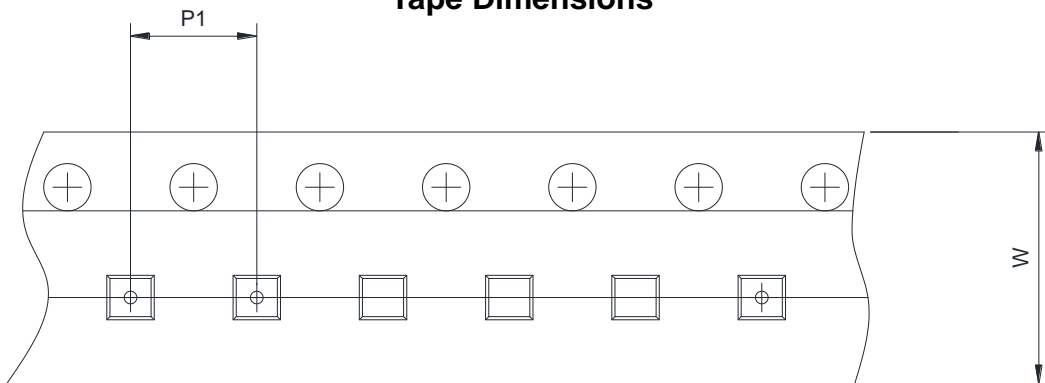
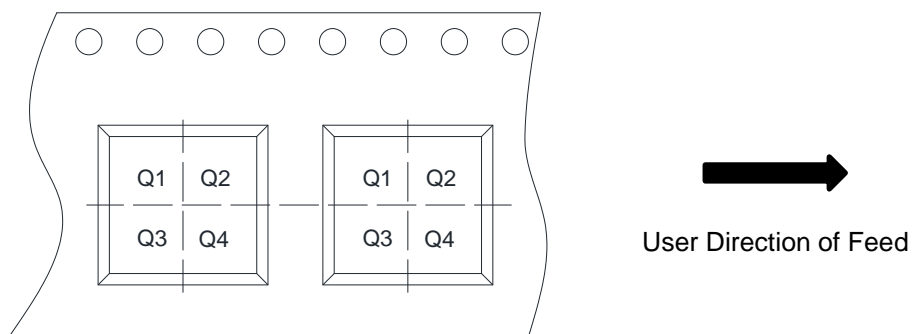
TOP VIEW



BOTTOM VIEW



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.80	0.90
A1	0.00	-	0.05
c	0.10	0.15	0.25
b	0.24	0.30	0.35
D	3.00 BSC		
D1	2.25	2.35	2.45
E	3.20 BSC		
E1	3.00 BSC		
E2	2.02	2.18	2.33
E3	0.48	0.58	0.68
E4	0.33 BSC		
e	0.65 BSC		
K	0.47	0.63	0.78
L	0.30	0.40	0.50
L1	0	-	0.10
$\theta$	0 °	10 °	12 °

**TAPE AND REEL INFORMATION**
**Reel Dimensions**

**Tape Dimensions**

**Quadrant Assignments For PIN1 Orientation In Tape**


RD	Reel Dimension	<input checked="" type="checkbox"/> 7inch	<input type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input checked="" type="checkbox"/> 8mm	<input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input checked="" type="checkbox"/> 4mm <input type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4